



Application and Features:

- The Nextron Multi-level Series offers 5.0mm, 5.08mm pin spacing. These series are designed in single level, bi-level and tri-level interlockable housings of the same pitch.
- Designed as a solution for limited space on the PC Board, the Multi-level series offers end to end stackability with snap together and stay together design.

Technical Data:

Material:

- HOUSING: NYLON (Glass Filled) UL 94V-0.
- Metal Housing: Brass Ni50u" + SnPb120u", plated.
- Screw: Steel, Zinc Plated. M2.6.*0.45

Electrical:

- · Current rating: 10 Amps / way (Max).
- Insulation resistance: 500M Ω (Min) / DC500V.
- Withstanding Voltage: 2000VAC (minute). test time= 60sec / 1pcs.
- · Operation voltage: 300 VAC.
- · Wire Range: 12-24 AWG.

Mechanical:

- Tightening Torque: 4 Kg-cm (Max).
- Operating temperature: -55°C to +105°C
- Solderability: 95 % coverage (Min). test temperature= 230°C ± 10°C. test time= 3sec ± 0.5sec.



